

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For	ca	pacitive	load,	derate	current	by 20%.

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 6)			1,000	V
RMS Reverse Voltage		V _{R(RMS)}	700	V
Average Rectified Output Current	@ T _A = +100°C	lo	1.0	А
Non-Repetitive Peak Forward Surge Curr Single Half Sine-Wave Superimposed on		I _{FSM}	30	А

Thermal Characteristics

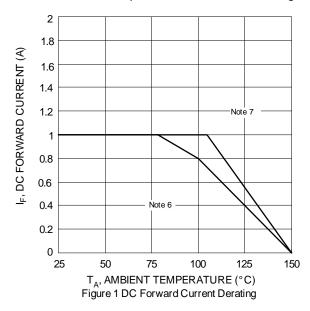
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 7)	R _{θJT}	31	°C/W
Typical Thermal Resistance, Junction to Air (Note 7)	R _{0JA}	83	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

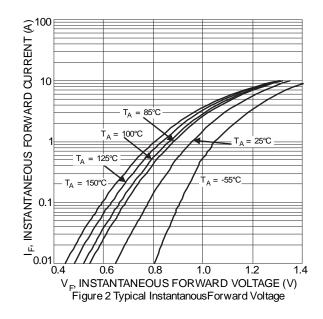
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V _{(BR)R}	1,000	—	—	V	I _R = 10μΑ
Forward Voltage Drop	V _F	_	0.95 0.83	1.3 —	V	I _F = 1A, T _J = +25°C I _F = 1A, T _J = +125°C
Leakage Current (Note 8)	I _R	_	0.2 5	5	μA	V _R = 1,000V, T _J = +25°C V _R = 1,000V, T _J = +125°C
Reverse Recovery Time	t _{RR}	_	140	500	ns	I _F = 0.5A, I _R = 1.0A, I _{RR} = 0.25A
Total Capacitance	CT	_	5	—	pF	$V_R = 4.0 V_{DC}, f = 1 MHz$

Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.1" x 0.15" copper pads.
Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pads.

8. Short duration pulse test used to minimize self-heating effect.







NEW PRODUCT

RS1MDFQ

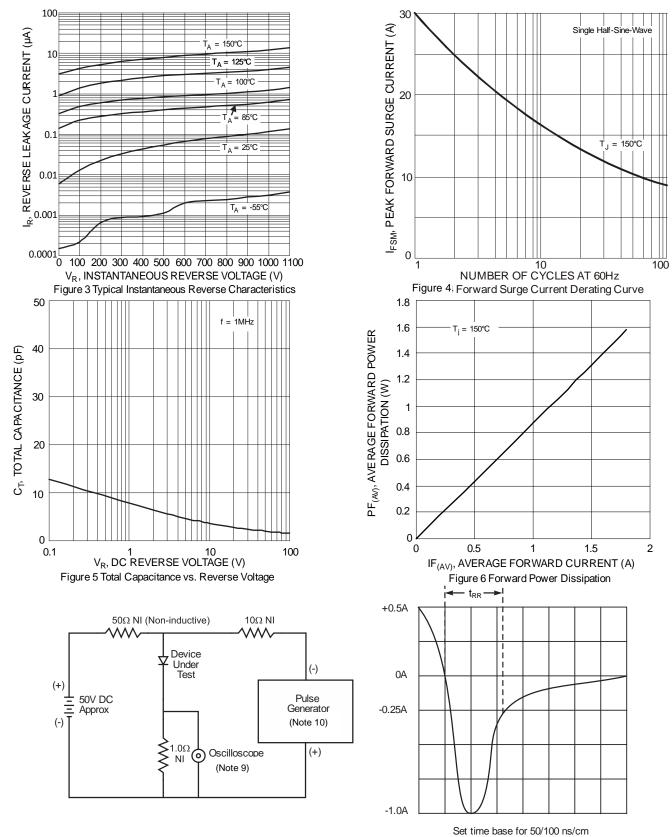


Figure 7 Reverse Recovery Time Characteristic and Test Circuit

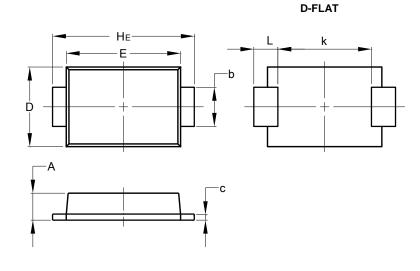
Notes: 9. Rise Time = 7.0ns max. Input Impedance = $1.0M\Omega$, 22pF. 10. Rise Time = 10ns max. Input Impedance = 50Ω .

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Package Outline Dimensions

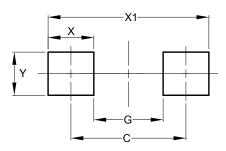
Please see http://www.diodes.com/package-outlines.html for the latest version.



D-FLAT					
Dim	Min	Max			
Α	0.90	1.10			
b	1.25	1.65			
С	0.10	0.40			
D	2.25	2.95			
Е	3.95	4.60			
k	2.80	-			
HE	5.00	5.60			
L	0.50	1.30			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
С	4.65		
G	2.80		
Х	1.85		
X1	6.50		
Y	1.70		

D-FLAT

RS1MDFQ	
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